L Number	Hits	Search Text	DB	Time stamp
38	3	(29/846,847).ccls. and (die or stamp or (forming adj member)) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:55
39	4	(438/22,23).ccls. and (die or stamp or (forming adj member)) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:55
40	1	(257/79,88).ccls. and (die or stamp or (forming adj member)) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:56
41	112	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and substrate and ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:57
42	61	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and substrate and ((metal or conduct$3) adj (film or layer)) and (die or stamp or (forming adj member)) with press$3	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:59
43	23	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and substrate and ((metal or conduct$3) adj (film or layer)) and ((die or stamp or (forming adj member)) with press$3) and ((die or stamp or (forming adj member)) with (remov$3 or releas$3))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 18:00
-	1	Transfer adj patterned adj metal adj cold-welding	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:15
-	2	(("5294870") or ("4769292")).PN.	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:18
-	1	("5925259").PN.	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:19
-	7	("2897066" | "3647508" | "3716911" | "4021279" | "5512131" | "5725788" | "5772905").PN.	USPAT	2004/03/10 18:21
-	11	5925259.URPN.	USPAT	2004/03/10 18:23
-	5	("5641611" | "5707745" | "5925259" | "6013538" | "6027630").PN.	USPAT	2004/03/10 18:29
-	6	("5641611" | "5707745" | "5925259" | "5998803" | "6013538" | "6027630").PN.	USPAT	2004/03/10 18:31
-	5247	(pattern$3) and substrate and (thin adj film) and (press$3) and die	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:38
-	3316	(pattern$3) same substrate and (thin adj film) and (press$3) and die	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:38
-	990	(pattern$3) same substrate same (thin adj film) and (press$3) and die	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:38
-	5	(pattern$3) same substrate same (thin adj film) and (press$3) and die and (cold adj weld$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:41
-	194	(pattern$3) same substrate same (thin adj film) same die and (press$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/10 18:42
-	18	5259926.URPN.	USPAT	2004/03/10 18:47
-	9	("5641611" | "5707745" | "5925259" | "5998803" | "6013538" | "6027630" | "6190940" | "6214631" | "6504096").PN.	USPAT	2004/03/11 09:38
-	6	("5641611" | "5707745" | "5925259" | "5998803" | "6013538" | "6027630").PN.	USPAT	2004/03/11 09:42
-	1	6468819.URPN.	USPAT	2004/03/11 09:42

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-	5	("5641611" | "5707745" | "5925259" | "6013538" | "6027630").PN.	USPAT	2004/03/11 09:43
-	2	6294398.URPN.	USPAT	2004/03/11 09:43
-	434	(pattern$3) same substrate same (electrode or (thin adj film)) same die and (press$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:00
-	325	(pattern$3) same substrate same (electrode or (thin adj film)) same die and (press$3) and remov$3	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:01
-	128	(pattern$3) same substrate same (electrode or (thin adj film)) same die and (press$3) and remov$3 same die	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:01
-	85	(pattern$3) same substrate same (electrode or (thin adj film)) same die and (press$3 same die) and (remov$3 same die)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:43
-	20	5900160.URPN.	USPAT	2004/03/11 10:12
-	35	("Re33581" | "2905539" | "3497377" | "3641354" | "3716359" | "4011009" | "4173075" | "4274706" | "4325779" | "4330175" | "4382657" | "4477158" | "4512848" | "4528260" | "4582566" | "4587213" | "4690715" | "4728591" | "4731155" | "4802951" | "4818336" | "4842633" | "4897325" | "4999489" | "5018829" | "5020879" | "5032216" | "5079600" | "5143854" | "5202227" | "5255273" | "5259926" | "5294369" | "5315436" | "5512131").PN.	USPAT	2004/03/11 10:23
-	1	("5512131").PN.	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:33
-	37	(pattern$3) same substrate same (electrode or (thin adj film)) same stamp$3 and (remov$3 same stamp)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:55
-	596	(die or stamp) and (cold adj weld$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:56
-	94	((die or stamp) same (cold adj weld$3)) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:56
-	90	((die or stamp) same (cold adj weld$3)) and substrate and (film or layer)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:57
-	64	((die or stamp) same (cold adj weld$3)) and substrate and (film or layer) and remov$3	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:57
-	50	((die or stamp) same (cold adj weld$3)) and substrate and (film or layer) and (remov$3 same (die or stamp))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:58
-	228	(die or stamp) same (cold adj weld$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 11:54
-	6	("5772905" | "5814885" | "5925259" | "6027630" | "6274508" | "6281038").PN.	USPAT	2004/03/11 11:27
-	35	("Re33581" | "2905539" | "3497377" | "3641354" | "3716359" | "4011009" | "4173075" | "4274706" | "4325779" | "4330175" | "4382657" | "4477158" | "4512848" | "4528260" | "4582566" | "4587213" | "4690715" | "4728591" | "4731155" | "4802951" | "4818336" | "4842633" | "4897325" | "4999489" | "5018829" | "5020879" | "5032216" | "5079600" | "5143854" | "5202227" | "5255273" | "5259926" | "5294369" | "5315436" | "5512131").PN.	USPAT	2004/03/11 11:48

-	598	(die or stamp or (forming adj member)) and (cold adj weld$3)	USPAT; US-PGPUB; IBM_TDB	2004/03/11 11:55
-	229	(die or stamp or (forming adj member)) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 11:55
-	79	(die or stamp or (forming adj member)) and (cold adj weld$3) and substrate and ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 11:58
-	6	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and (cold adj weld$3) and substrate and ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:00
-	6	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and (cold adj weld$3) and substrate and ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:03
-	6	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion)) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:02
-	20	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion) or indentation) and (cold adj weld$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:02
-	1746	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion) or indentation) and substrate and ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:04
-	711	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion) or indentation) and substrate with ((metal or conduct$3) adj (film or layer))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:04
-	99	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion) or indentation) and substrate with ((metal or conduct$3) adj (film or layer)) and ((press$3 or forc@3) with (die or stamp or (forming adj member)))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:06
-	9	((die or stamp or (forming adj member)) with ((rais$3 or project$3 or protrud$3) adj portion) or indentation) and substrate with ((metal or conduct$3) adj (film or layer)) and ((press$3 or forc@3) with (die or stamp or (forming adj member))) and ((releas$3 or remov@3) with (die or stamp or (forming adj member)))	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:06
-	1	("5707745").PN.	USPAT; US-PGPUB; IBM_TDB	2004/03/11 16:26
-	130	heterostructure same polymer	USPAT; US-PGPUB; IBM_TDB	2004/03/11 16:26
-	88	heterostructure with polymer	USPAT; US-PGPUB; IBM_TDB	2004/03/11 16:26
-	5	heterostructure near polymer	USPAT; US-PGPUB; IBM_TDB	2004/03/11 16:26

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